imall

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1.5V Drive Pch+Pch MOSFET

TT8J1

Structure

Silicon P-channel MOSFET

Features

1) Low On-resistance.

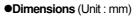
- 2) High Power Package.
- 3) Low voltage drive. (1.5V)

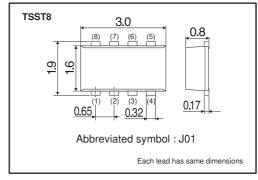
Applications

Switching

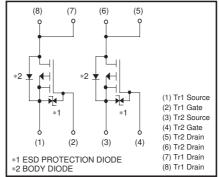
Packaging specifications

	Package	Taping		
Туре	Code	TR		
	Basic ordering unit (pieces)	3000		
TT8J1		0		









•Absolute maximum ratings (Ta=25°C) <It is the same ratings for the Tr1 and Tr2.>

Parameter		Symbol		Limits	Unit
Drain-source voltage		VDSS		-12	V
Gate-source voltage		V _{GSS}		±10	V
Duala autorat	Continuous	ID		±2.5	A
Drain current	Pulsed	IDP	*1	±10	A
Source current (Body diode)	Continuous	ls		-0.8	A
	Pulsed	I _{SP}	*1	-10	A
Total power dissipation		Pp	*2	1.25	W / TOTAL
		FD		1.0	W / ELEMENT
Channel temperature		Tch		150	°C
Range of Storage temperature		Tstg		-55 to +150	°C
∗1 Pw≤10μs, Duty cycle≤1%					

*2 Mounted on a ceramic board

Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to ambient	Dth(ch.c)	100	°C / W / TOTAL
	Rth(ch-a)	125	°C / W / ELEMENT

* Mounted on a ceramic board

•Electrical characteristics (Ta=25°C)

< It is the same characteristics for the Tr1 and Tr2.>

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	
Gate-source leakage	lgss	_	_	±10	μΑ	Vgs=±10V, Vds=0V	
Drain-source breakdown voltage	V(BR) DSS	-12	-	_	V	$I_D = -1mA$, $V_{GS} = 0V$	
Zero gate voltage drain current	IDSS	_	-	-1	μA	$V_{DS} = -12V, V_{GS} = 0V$	
Gate threshold voltage	VGS (th)	-0.3	-	-1.0	V	$V_{DS} = -6V$, $I_D = -1mA$	
Static drain-source on-state resistance	R _{DS} (on)*	-	44	61	mΩ	$I_D = -2.5A, V_{GS} = -4.5V$	
		-	60	84	mΩ	$I_D = -1.2A, V_{GS} = -2.5V$	
		-	81	121	mΩ	$I_D = -1.2A$, $V_{GS} = -1.8V$	
		-	110	220	mΩ	ID= -0.5A, VGS= -1.5V	
Forward transfer admittance	Y _{fs} *	3.5	-	_	S	$V_{DS} = -6V, I_{D} = -2.5A$	
Input capacitance	Ciss	-	1350	-	pF	V _{DS} =-6V	
Output capacitance	Coss	-	130	_	pF	V _{GS} =0V	
Reverse transfer capacitance	Crss	-	125	_	pF	f=1MHz	
Turn-on delay time	td (on) *	-	9	-	ns	V _{DD} ≒ –6V	
Rise time	tr *	-	35	-	ns	VGs= -4.5V ID= -1.2A	
Turn-off delay time	td (off) *	-	130	_	ns	$R_{L} = 5\Omega$	
Fall time	tr *	-	85	_	ns	$R_{G}=10\Omega$	
Total gate charge	Qg *	-	13	-	nC	V _{DD} ≒-6V	
Gate-source charge	Q _{gs} *	-	2.5	-	nC	V _{GS} =-4.5V Ip=-2.5A	
Gate-drain charge	Q _{gd} *	-	2.0	-	nC	$R_L = 2.4\Omega / R_G = 10\Omega$	

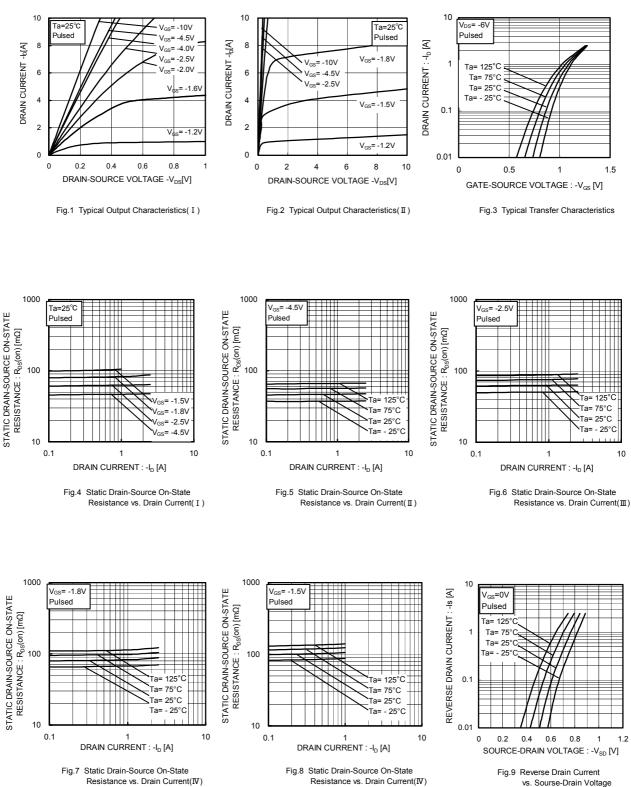
*Pulsed

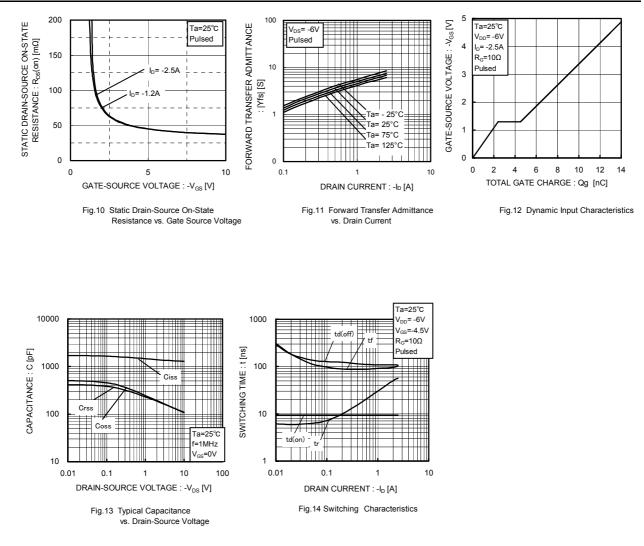
•Body diode characteristics (Source-drain) (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	Vsd*	-	-	-1.2	V	I _S = -2.5A, V _{GS} =0V

* Pulsed

•Electrical characteristic curves





Measurement circuits

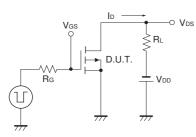


Fig.1-1 Switching Time Measurement Circuit

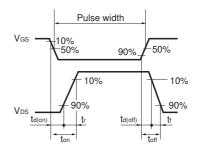


Fig.1-2 Switching Waveforms

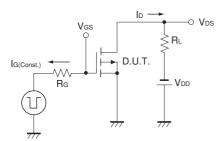


Fig.2-1 Gate Charge Measurement Circuit

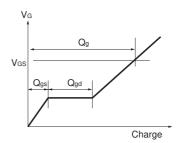


Fig.2-2 Gate Charge Waveform

Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

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